



Material Content Data Sheet



Sales Product Name		IPD036N04L G		Issued		20. July 2018		
MA#		MA000391296						
Package		PG-TO252-3-311		Weight*		314.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	0.72	0.72	7151	7151
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		456	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	copper	7440-50-8	143.098	45.55	45.61	455449	456042
wire	non noble metal	aluminium	7429-90-5	3.786	1.20	1.20	12049	12049
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.956	0.62		6225	
	plastics	brominated resin	-	2.096	0.67		6670	
	organic material	carbon black	1333-86-4	2.235	0.71		7115	
	plastics	epoxy resin	-	18.861	6.00		60032	
	inorganic material	silicondioxide	60676-86-0	114.565	36.46	44.46	364636	444678
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11904	11904
plating	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
solder	noble metal	silver	7440-22-4	0.053	0.02		170	
	non noble metal	tin	7440-31-5	0.043	0.01		136	
	non noble metal	lead	7439-92-1	2.035	0.65	0.68	6478	6784
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	61037	61116
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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